DATA SHEET

TDA8424
Hi-Fi stereo audio processor; I²C-bus

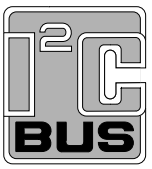
Product specification
File under Integrated Circuits, IC02

September 1992

Philips Semiconductors

PHILIPS

Hi-Fi stereo audio processor; I²C-bus TDA8424



FEATURES

- Mode selector
- Spatial stereo, stereo and forced mono switch
- Volume and balance control
- Bass, treble and mute control
- Power supply with power-on reset

GENERAL DESCRIPTION

The TDA8424 is monolithic bipolar integrated stereo sound circuit with a loudspeaker channel facility, digitally controlled via the I²C-bus for application in hi-fi audio and television sound.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{CC}	positive supply voltage (pin 4)	10.8	12.0	13.2	V
V_I	input signal handling	2	–	–	V
V_i	input sensitivity with full power at the output stage	–	300	–	mV
(S+N)/N	signal plus noise-to-noise ratio	–	86	–	dB
THD	total harmonic distortion	–	0.05	–	%
α_{cs}	channel separation	–	80	–	dB
G_{vol}	volume control range	–64	–	+6	dB
G_{tre}	treble control range	–12	–	+12	dB
G_{bass}	bass control range	–12	–	+15	dB

ORDERING INFORMATION

EXTENDED TYPE NUMBER	PACKAGE			
	PINS	PIN POSITION	MATERIAL	CODE
TDA8424	20	DIL	plastic	SOT146(1)

Note

1. SOT146-1; 1996 December 3.

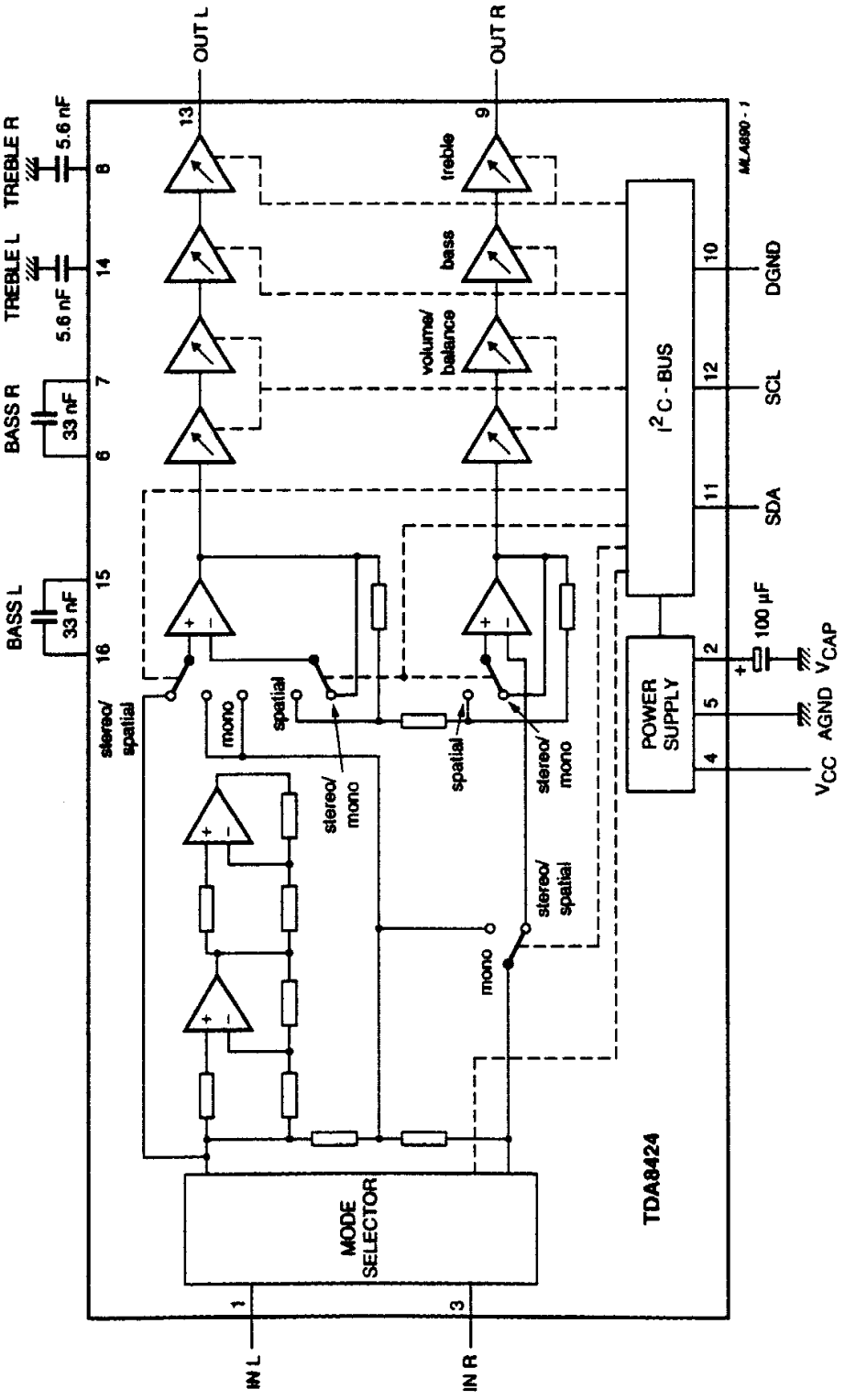


Fig.1 Block diagram.

PINNING

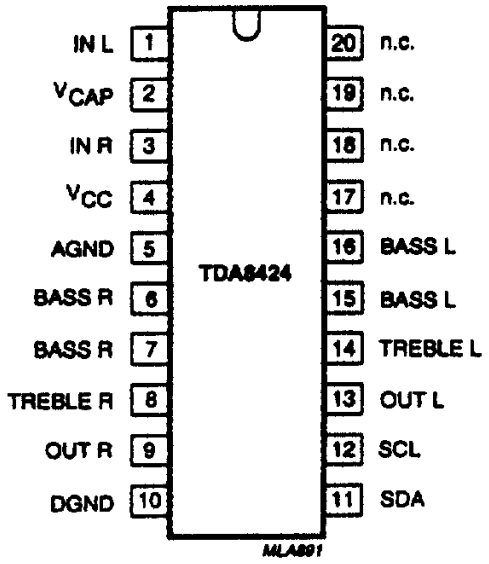


Fig.2 Pin configuration.

SYMBOL	PIN	DESCRIPTION
IN L	1	left channel input
V_{CAP}	2	decoupling capacitor
IN R	3	right channel input
V_{CC}	4	positive supply voltage
AGND	5	analog ground
BASS R	6	right channel bass control
BASS R	7	right channel bass control
TREBLE R	8	right channel treble control
OUT R	9	right channel output
DGND	10	digital ground
SDA	11	serial data input/output
SCL	12	serial clock input
OUT L	13	left channel output
TREBLE L	14	left channel treble control
BASS L	15	left channel bass control
BASS L	16	left channel bass control
n.c.	17	not connected
n.c.	18	not connected
n.c.	19	not connected
n.c.	20	not connected

FUNCTIONAL DESCRIPTION

Mode selector

The mode selector selects between stereo, sound A and sound B (in the event of bi-lingual transmission) for OUT R and OUT L.

Volume control and balance

The volume control consists of two stages (left and right). In each part the gain can be adjusted between +6 dB and −64 dB in steps of 2 dB. An additional step allows an attenuation of ≥ 80 dB. Both parts can be controlled independently over the whole range, which allows the balance to be varied by controlling the volume of left and right output channels.

Stereo, spatial stereo and forced mono mode

It is possible to select three modes: stereo, spatial stereo or forced mono. The spatial stereo mode handles stereo transmissions and the forced mono can be used in the event of stereo signals.

Bass control

The bass control can be switched from an emphasis of 15 dB to an attenuation of 12 dB for low frequencies in steps of 3 dB.

Treble control

The treble control stage can be switched from +12 dB to −12 dB in steps of 3 dB.

Bias and power supply

The TDA8424 includes a bias and power supply stage, which generates a voltage of 0.5 V_{CC} with a low output impedance and injector currents for the logic part.

Power-on reset

The on-chip power-on reset circuit sets the mute bit to active, which mutes both parts of the treble amplifier. The muting can be switched by transmission of the mute bit.

I²C-bus receiver and data handling

BUS SPECIFICATION

The TDA8424 is controlled via the 2-wire I²C-bus by a microcontroller.
The two wires (SDA - serial data, SCL - serial clock) carry information between the devices connected to the bus.
Both SDA and SCL are bi-directional lines, connected to a positive supply voltage via a pull-up resistor.
When the bus is free both lines are HIGH.
The data on the SDA line must be stable during the HIGH period of the clock. The HIGH or LOW state of the data line can only change when the clock on the SCL line is LOW.
The set-up and hold times are specified in the AC CHARACTERISTICS.
A HIGH-to-LOW transition of the SDA line while SCL is HIGH is defined as a start condition.
A LOW-to-HIGH transition of the SDA line while SCL is HIGH is defined as a stop condition.
The bus receiver will be reset by the reception of a start condition. The bus is considered to be busy after the start condition.
The bus is considered free again after a stop condition.

Module address

Data transmission to the TDA8424 starts with the module address MAD.

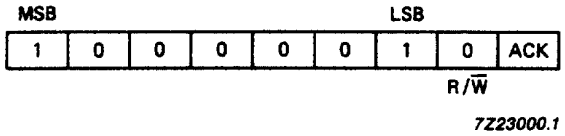


Fig.3 TDA8424 module address.

Subaddress

After the module address byte a second byte is used to select the following functions:

- Volume left, volume right, bass, treble and switch functions

The subaddress SAD is stored within the TDA8424. Table 1 defines the coding of the second byte after the module address MAD.

The automatic increment feature of the slave address enables a quick slave receiver initialization, within one transmission, by the I²C-bus controller (see Fig.5).

Table 1 Second byte after module address MAD

	128	64	32	16	8	4	2	1
	MSB							LSB
FUNCTION	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Volume left	0	0	0	0	0	0	0	0
Volume right	0	0	0	0	0	0	0	1
Bass	0	0	0	0	0	0	1	0
Treble	0	0	0	0	0	0	1	1
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	0
Switch functions	0	0	0	0	1	0	0	0
					subaddress SAD			

Definition of 3rd byte

A third byte is used to transmit data to the TDA8424. Table 2 defines the coding of the third byte after module address MAD and subaddress SAD.

Table 2 Third byte after module address MAD and subaddress SAD

		MSB							LSB
FUNCTION		**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Volume left	VL	1	1	V05	V04	V03	V02	V01	V00
Volume right	VR	1	1	V15	V14	V13	V12	V11	V10
Bass	BA	1	1	1	1	BA3	BA2	BA1	BA0
Treble	TR	1	1	1	1	TR3	TR2	TR1	TR0
		1	1	1	1	1	1	1	1
		1	1	1	1	1	1	1	1
		1	1	1	1	1	1	1	1
		1	1	1	1	1	1	1	1
Switch functions	S1	1	1	MU	EFL	STL	ML1	ML0	1

Truth tables

Tables 3, 4 and 5 are truth tables for the switch functions

Table 3 Mode selector

FUNCTION	ML1	ML0	IS
Stereo	1	1	1(1)
Sound A	0	1	1(1)
Sound B	1	0	1(1)

Note

1. Must be set to logic 1

Table 4 Stereo/spatial stereo/forced mono

CHOICE	STL	EFL
Spatial stereo	1	1
Stereo	1	0
Forbidden status	0	1
Forced mono	0	0

Table 5 Mute (see note 1)

MUTE	MU
Active; automatic after POR	1
Not active	0

Note

1. POR = Power-on reset.

Tables 6, 7 and 8 are truth tables for the volume, bass and treble controls

Table 6 Volume control

2 dB/STEP (dB)	V × 5	V × 4	V × 3	V × 2	V × 1	V × 0
6	1	1	1	1	1	1
4	1	1	1	1	1	0
2	1	1	1	1	0	1
0	1	1	1	1	0	0
–2	1	1	1	0	1	1
–4	1	1	1	0	1	0
–6	1	1	1	0	0	1
–8	1	1	1	0	0	0
–10	1	1	0	1	1	1
–20	1	1	0	0	1	0
–30	1	0	1	1	0	1
–40	1	0	1	0	0	0
–50	1	0	0	0	1	1
–60	0	1	1	1	1	0
–62	0	1	1	1	0	1
–64	0	1	1	1	0	0
–80	0	1	1	0	1	1

Table 7 Bass control

3 dB/STEP (dB)	BA3	BA2	BA1	BA0
15	1	0	1	1
12	1	0	1	0
9	1	0	0	1
6	1	0	0	0
3	0	1	1	1
0	0	1	1	0
–3	0	1	0	1
–6	0	1	0	0
–9	0	0	1	1
–12	0	0	1	0

Table 8 Treble control

3 dB/STEP (dB)	TR3	TR2	TR1	TR0
12	1	0	1	0
9	1	0	0	1
6	1	0	0	0
3	0	1	1	1
0	0	1	1	0
–3	0	1	0	1
–6	0	1	0	0
–9	0	0	1	1
–12	0	0	1	0

Sequence of data transmission

After a power-on reset all five functions have to be adjusted with five data transmissions. It is recommended that data information for switch functions are transmitted last because all functions have to be adjusted when the muting is switched off. The sequence of transmission of other data information is not critical.

The order of data transmission is shown in Figures 4 and 6. The number of data transmissions is unrestricted but before each data byte the module address MAD and the correct subaddress SAD is required.

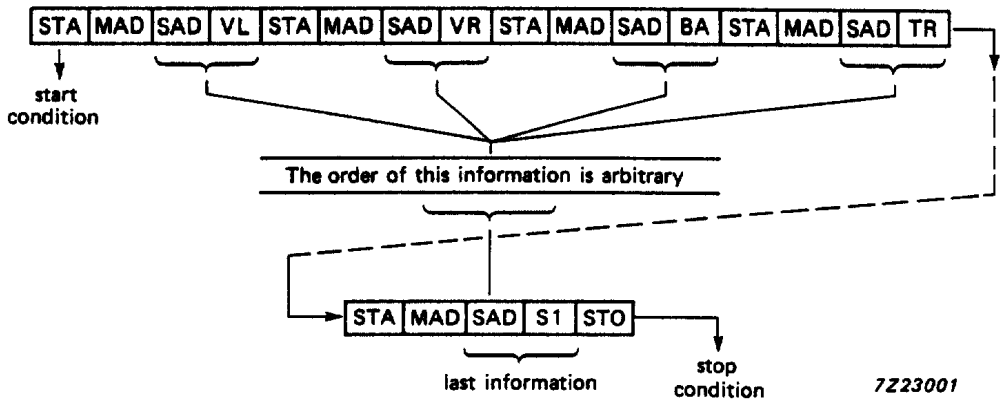


Fig.4 Data transmission after a power-on reset.

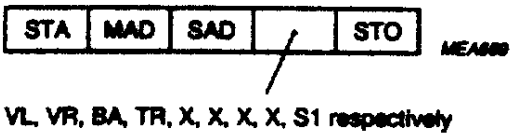


Fig.5 Data transmission after a power-on reset with auto increment.

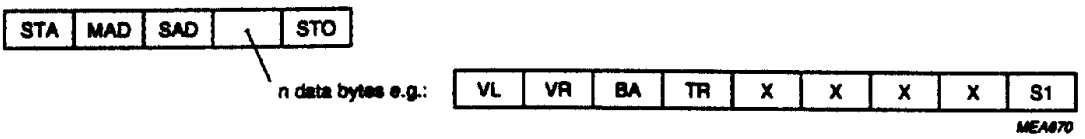


Fig.6 Data transmission except after a power-on reset.

LIMITING VALUES

In accordance with Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{CC}	supply voltage	0	16	V
V_{cap}	voltage range for pins with external capacitors	0	V_{CC}	V
$V_{SDA, SCL}$	voltage range for pins 11 and 12	0	V_{CC}	V
$V_{I/O}$	voltage range at pins 1, 3, 9, 11, 12 and 13	0	V_{CC}	V
I_O	output current at pins 9 and 13	–	45	mA
P_{tot}	total power dissipation at $T_{amb} < 70$ °C	–	450	mW
T_{amb}	operating ambient temperature range	0	+70	°C
T_{stg}	storage temperature range	–25	+150	°C
V_{stat}	electrostatic handling	see note 1		

Note

1. Electrostatic handling Human body model: C = 100 pF, R = 1.5 kΩ and V ≥ 3 kV; charge device model: C = 200 pF, R = 0 Ω and V ≥ 400 V.

DC CHARACTERISTICS

V_{CC} = 12 V; T_{amb} = 25 °C; unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies						
V_{CC}	supply voltage range		10.8	12.0	13.2	V
I_{CC}	supply current	at V_{CC} = 12 V	–	26	35	mA
V_{ref}	internal reference voltage		5.4	$0.5V_{CC}$	6.6	V
V_I	internal voltage at pins 1 and 3	DC voltage internally generated; capacitive coupling recommended	–	V_{ref}	–	V
V_O	internal voltage at pins 9 and 13		–	V_{ref}	–	V
SDA; SCL (pins 11 and 12)						
V_{IH}	HIGH level input voltage		3.0	–	V_{CC}	V
V_{IL}	LOW level input voltage		–3.0	–	1.5	V
I_{IH}	HIGH level input current		–	–	+10	µA
I_{IL}	LOW level input current		–10	–	–	µA
	output voltage at pins with external capacitors					
$V_{cap.n}$	pins 6 to 8, 14 to 16		–	V_{ref}	–	V
$V_{cap.2}$	pin 2		–	V_{CC}–0.3	–	V

AC CHARACTERISTICS

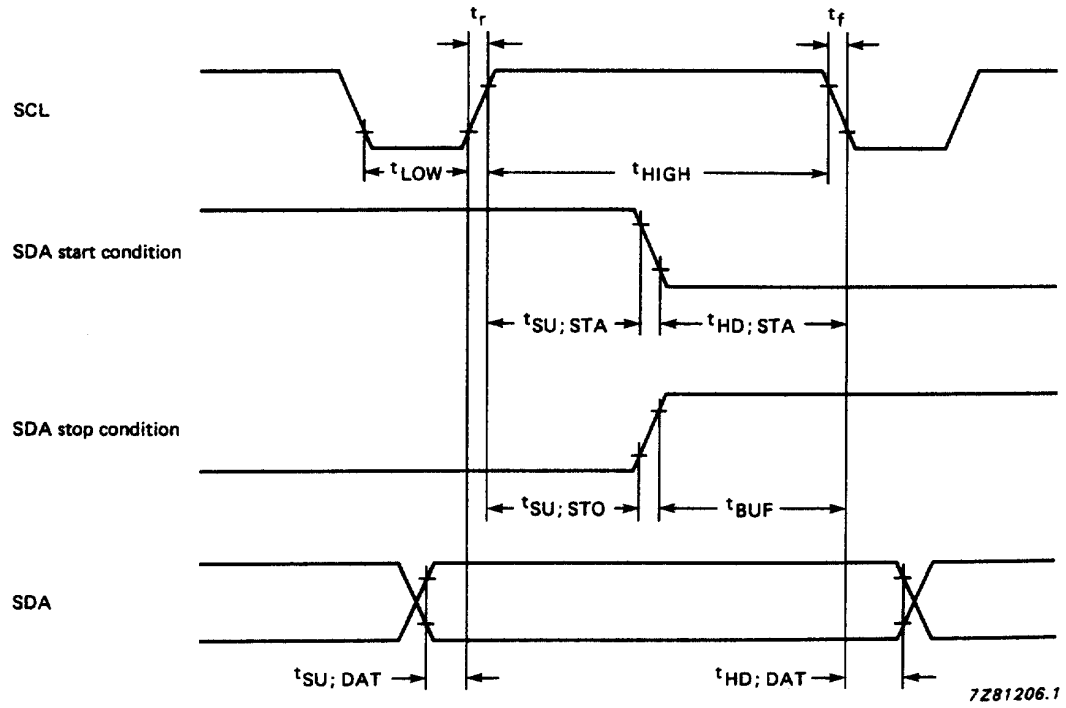
V_{CC} = 12 V; bass/treble in linear position; stereo mode; spatial stereo off; R_L > 10 kΩ; C_L < 1000 pF; T_{amb} = 25 °C; unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I²C-bus timing (see Fig.7)						
SDA, SCL (PINS 11 AND 12)						
f_{SCL}	clock frequency range		0	–	100	kHz
t_{HIGH}	clock HIGH period		4	–	–	µs
t_{LOW}	clock LOW period		4.7	–	–	µs
t_r	SCL rise time		–	–	1	µs
t_f	SCL fall time		–	–	0.3	µs
$t_{SU;STA}$	set-up time for start condition		4.7	–	–	µs
$t_{HD;STA}$	hold time for start condition		4	–	–	µs
$t_{SU;STO}$	set-up time for stop condition		4.7	–	–	µs
t_{BUF}	time bus must be free before a new transmission can start		4.7	–	–	µs
$t_{SU;DAT}$	data set-up time		250	–	–	ns
Inputs						
IN L (PIN 1) IN R (PIN 3)						
$V_{i(RMS)}$	input signal handling (RMS value)	at V_u = –12 dB; THD ≤ 0.5%	2	–	–	V
R_i	input resistance		20	30	40	kΩ
f	frequency response (0.5 dB)		20	–	20 000	Hz
Outputs						
OUT R (PIN 9) OUT L (PIN 13)						
$V_{o(RMS)}$	output voltage range (RMS value)	at $V_{i(max)}$ ≤ 2 V; THD ≤ 0.7%	0.6	–	–	V
R_L	load resistance		10	–	–	kΩ
Z_O	output impedance		–	–	100	Ω
(S+N)/N	signal plus noise-to-noise ratio	weighted in accordance with CCIR 468-2; V_o = 600 mV				
	gain = 6 dB		–	78	–	dB
	gain = 0 dB		–	86	–	dB
	gain ≤ –20 dB		–	68	–	dB
THD	total harmonic distortion	f = 20 Hz to 12.5 kHz				
	gain = +6 dB to –40 dB	$V_{i(RMS)}$ = 0.3 V	–	0.05	–	%
	gain = 0 dB to –40 dB	$V_{i(RMS)}$ = 0.6 V	–	0.07	0.4	%
	gain = –12 dB to –40 dB	$V_{i(RMS)}$ = 2.0 V	–	0.1	–	%

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Outputs						
α_{cs}	channel separation at 10 kHz	gain = 0 dB	–	80	–	dB
RR_{100}	ripple rejection	f_{ripple} = 100 Hz; $V_{r(RMS)}$ < 200 mV gain = 0 dB	–	50	–	dB
α_L	crosstalk attenuation from logic inputs to AF outputs	gain = 0 dB	–	100	–	dB
Volume control (see Table 6)						
	control range (36 steps)	f = 1 kHz				
G_{max}	maximum voltage gain	6 dB step	5	6	–	dB
G_{min}	minimum voltage gain	–64 dB step	–63	–64	–	dB
G_{mute}	mute position		–80	–90	–	dB
G_{err}	gain tracking error; balance in mid-position		–	–	2	dB
G_{step}	step resolution					
	gain from +6 dB to –40 dB		1.5	2.0	2.5	dB/step
	gain from –42 dB to –64 dB		1.0	2.0	3.0	dB/step
Treble control (see Table 8)						
	control range	C_{8-5}; C_{14-5} = 5.6 nF				
G_{emp}	maximum emphasis at 15 kHz with respect to linear position		11	12	13	dB
G_{att}	maximum attenuation at 15 kHz with respect to linear position		11	12	13	dB
G_{step}	resolution		2.5	3.0	3.5	dB/step
Bass control (see Table 7)						
	control range	C_{6-7}; C_{15-16} = 33 nF				
G_{emp}	maximum emphasis at 40 Hz with respect to linear position		14	15	16	dB
G_{att}	maximum attenuation at 40Hz with respect to linear position		11	12	13	dB
G_{step}	resolution		2.5	3.0	3.5	dB/step
Spatial function						
α	antiphase crosstalk		–	52	–	%

Note to the characteristics

1. Balance is obtained via software by different volume settings in both channels (left and right).



$t_{SU;STA}$ = start code set-up time.
$t_{HD;STA}$ = start code hold time.
$t_{SU;STO}$ = stop code set-up time.

t_{BUF} = bus free time.
$t_{SU;DAT}$ = data set-up time.
$t_{HD;DAT}$ = data hold time.

Fig.7 Timing requirements for I²C-bus.

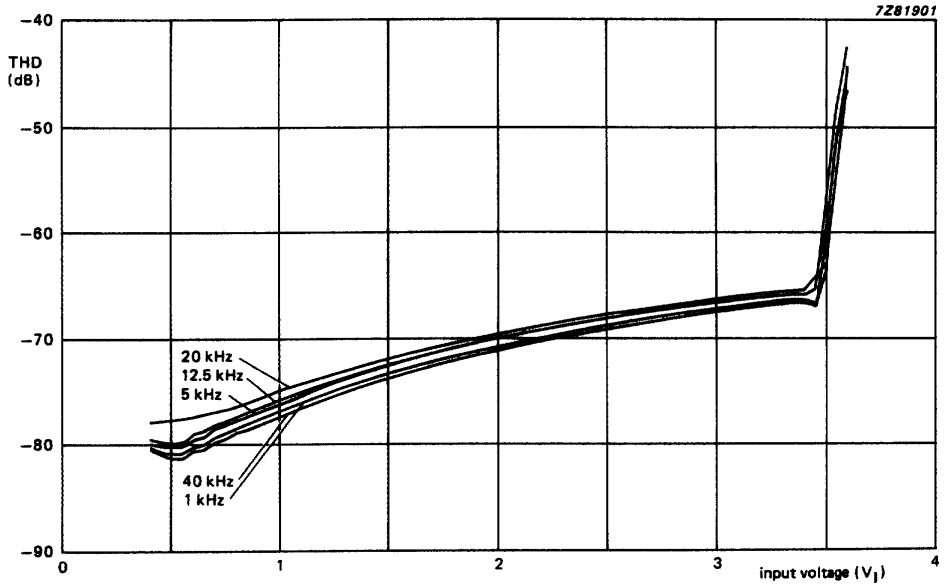


Fig.8 Input signal handling capability; gain = –10 dB; R_S = 600 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.

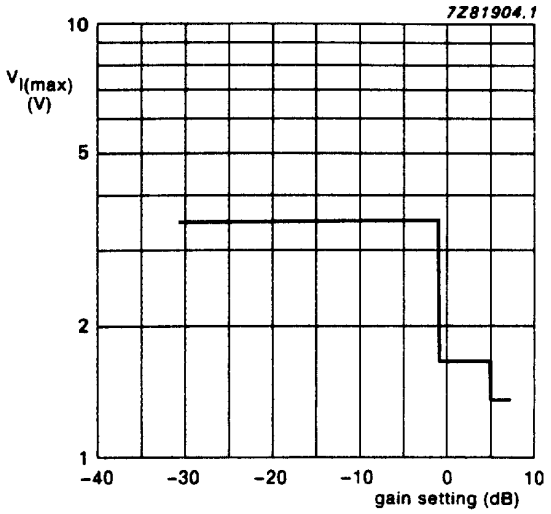


Fig.9 Input signal handling capability plotted against gain setting; THD = −60 dB; f = 1 kHz; R_S = 600 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.

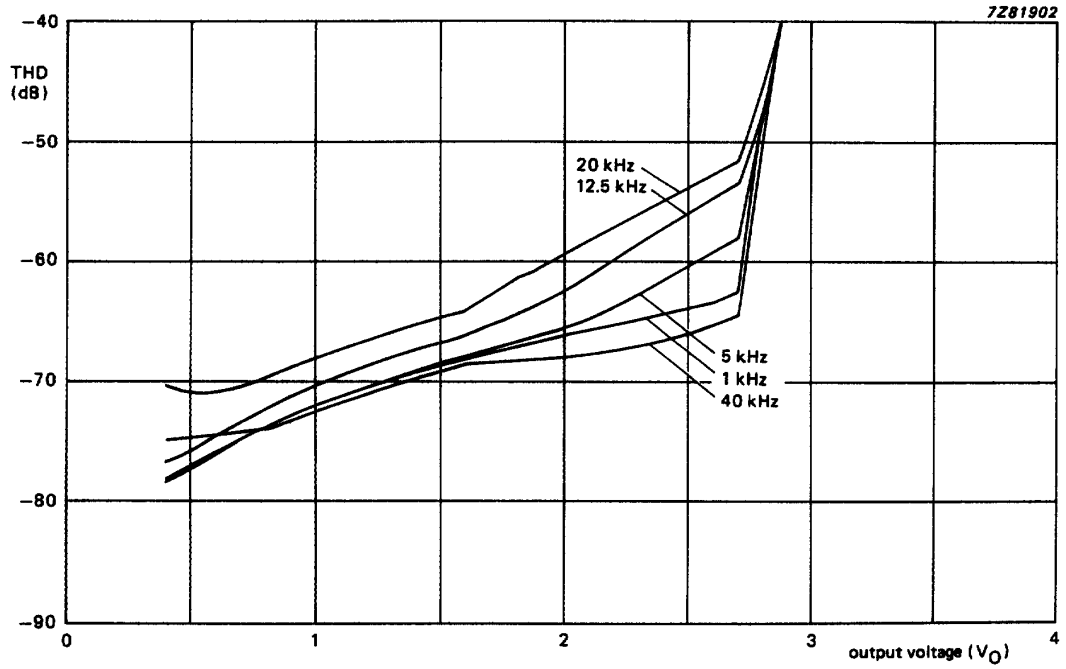
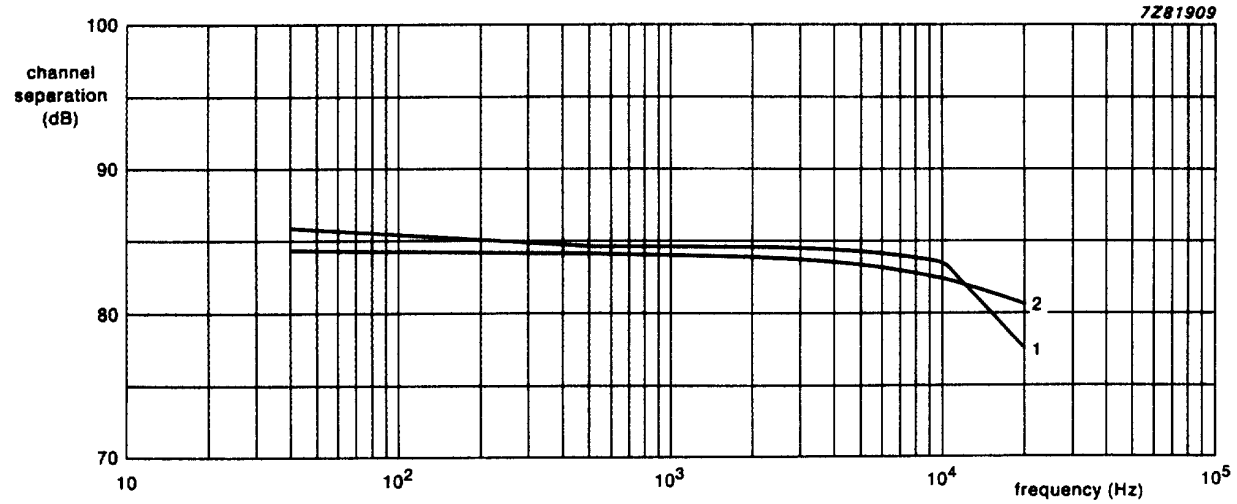


Fig.10 Output signal handling capability; gain = 6 dB; R_S = 600 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.



(1) gain = 0 dB; V_i = 1.0 V.
(2) gain = 6 dB; V_i = 0.5 V.

Fig.11 Stereo channel separation as a function of frequency; R_S = 0 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.

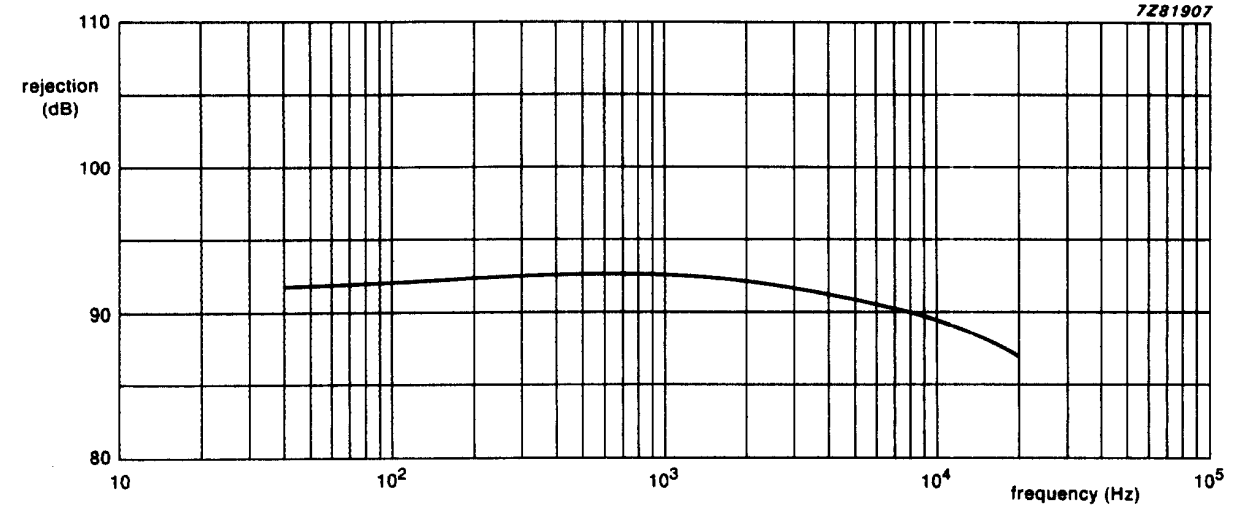


Fig.12 Mute signal rejection as a function of frequency; gain = 0 dB; V_i = 1.0 V; R_S = 0 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.

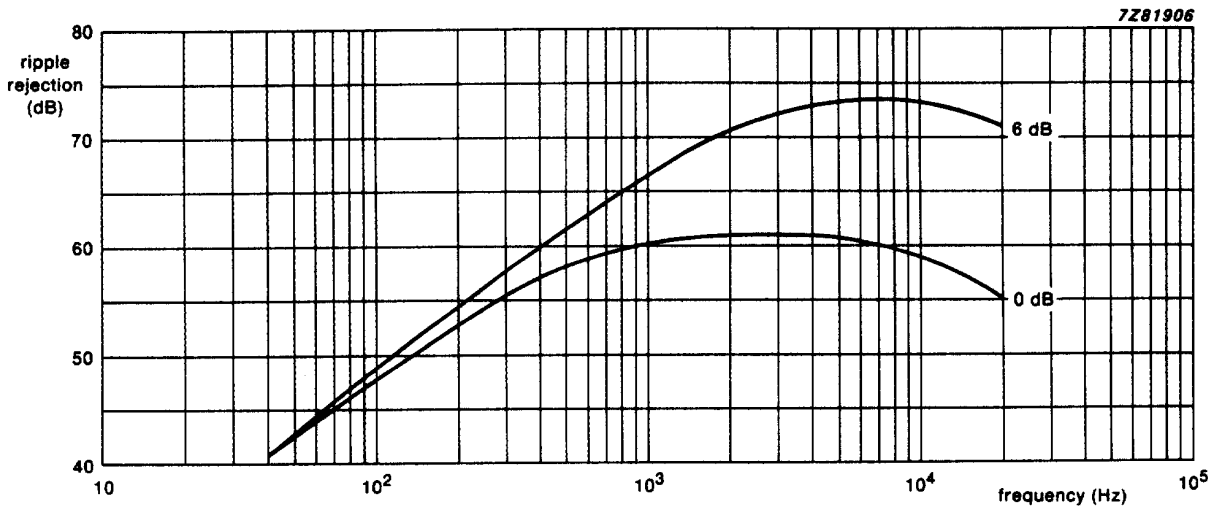


Fig.13 Ripple rejection as a function of frequency; V_{ripple} = 0.3 V (RMS); R_S = 0 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.

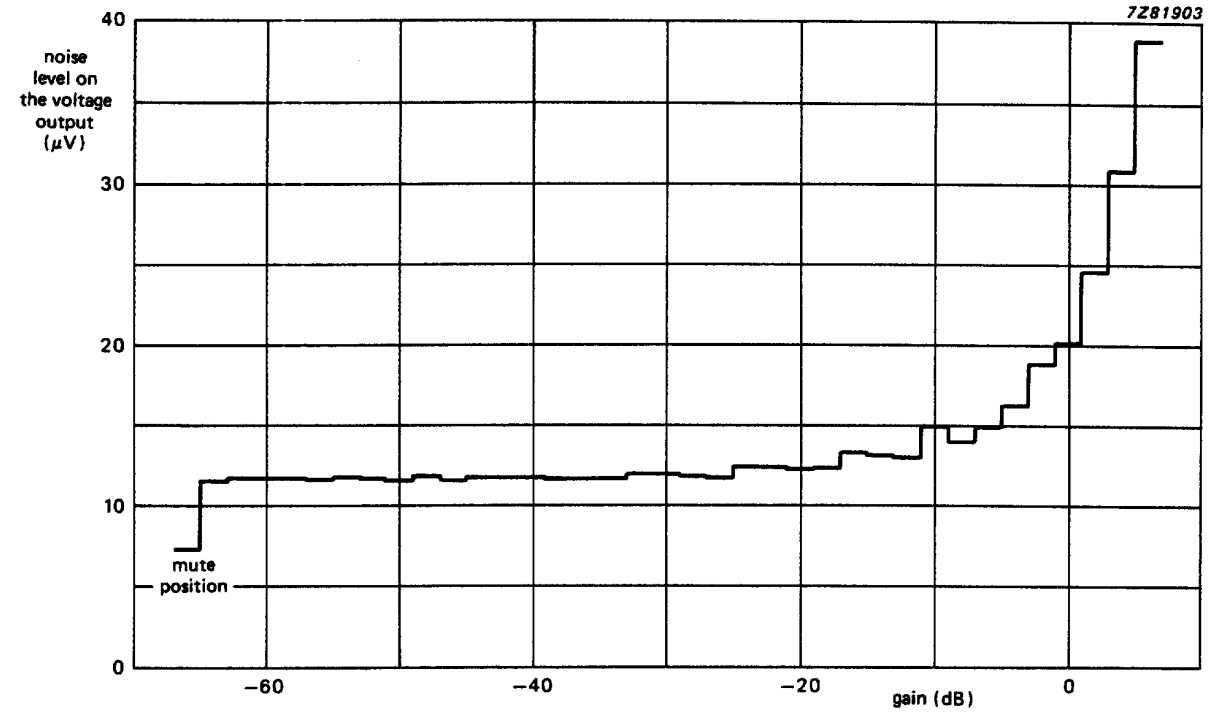


Fig.14 Noise output voltage as a function of gain; weighted CCIR 468 quasi peak gain, +6 dB to −64 dB; V_i = 0 V; R_S = 0 Ω; R_L = 10 kΩ; bass/treble = 0 dB; V_{CC} = 12 V.

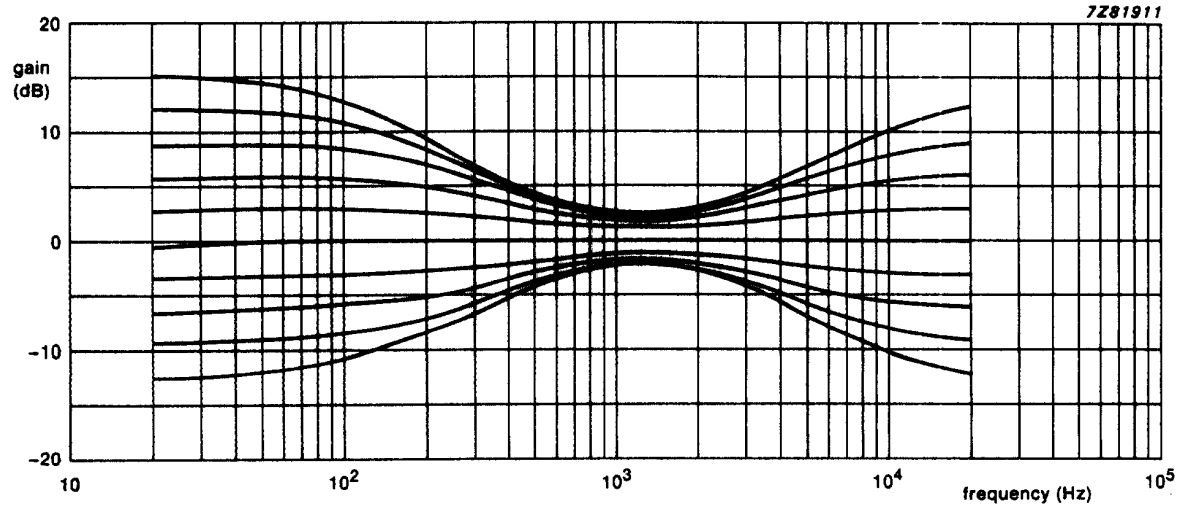


Fig.15 Frequency response of bass and treble control; bass and treble gain settings = –12 dB to +15 dB; gain = 0 dB; V_i = 0.1 V; R_S = 600 Ω; R_L = 10 kΩ; V_{CC} = 12 V.

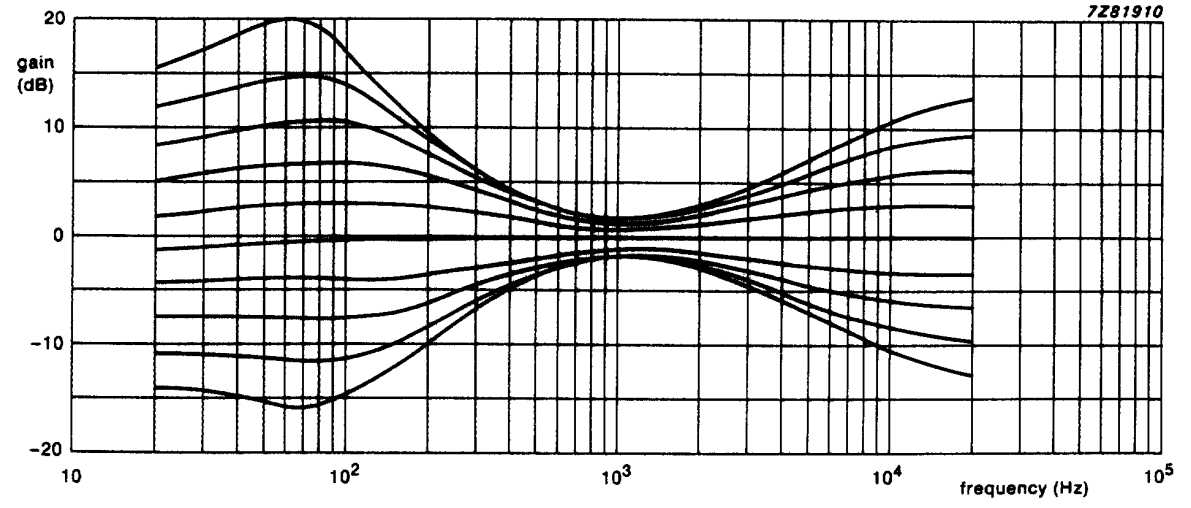


Fig.16 Tone control with T-filter.

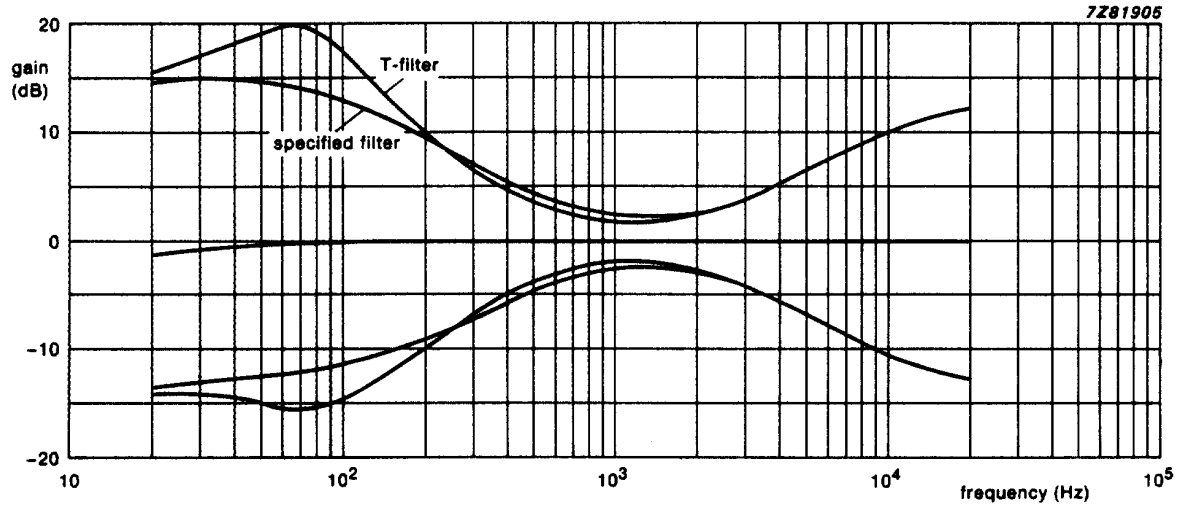


Fig.17 Tone control.

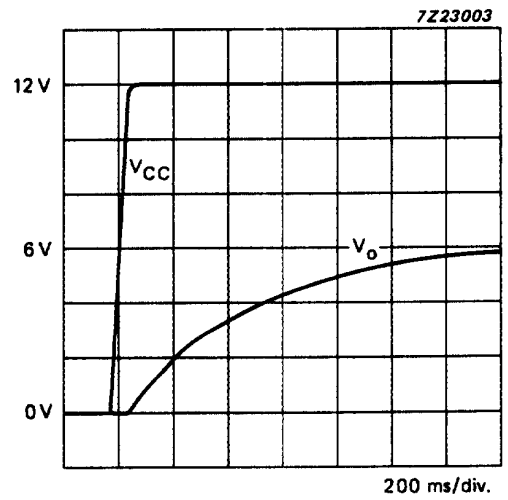


Fig.18 Turn-on behaviour; C = 2.2 µF; R_L = 10 kΩ.

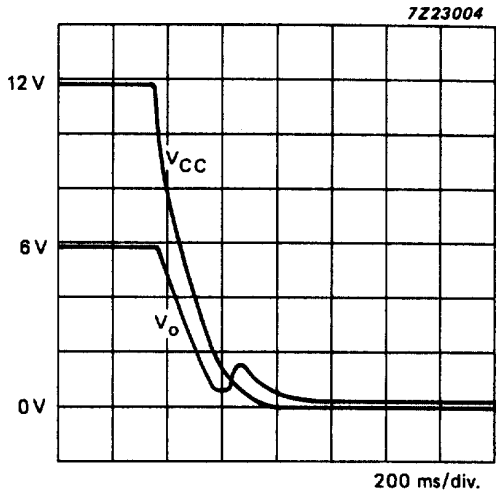


Fig.19 Turn-off behaviour; without modulation.

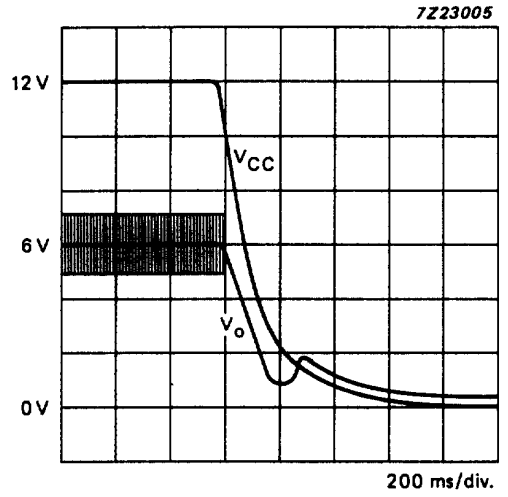
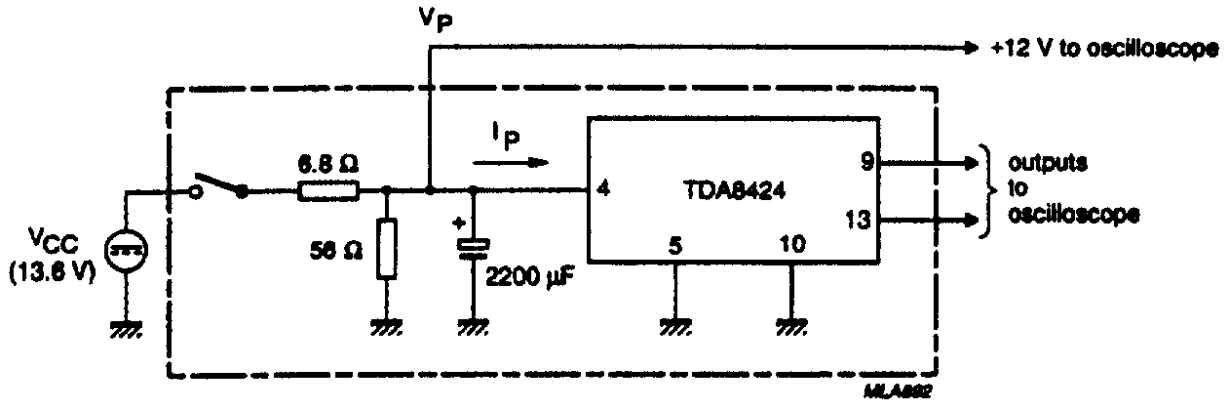


Fig.20 Turn-off behaviour; with modulation (shaded area).



I_{CC} = 25 mA
I_{load} = 239 mA
t_{on} = 15 ms
t_{off} = 110 ms

Fig.21 Turn-on/off power supply circuit diagram.

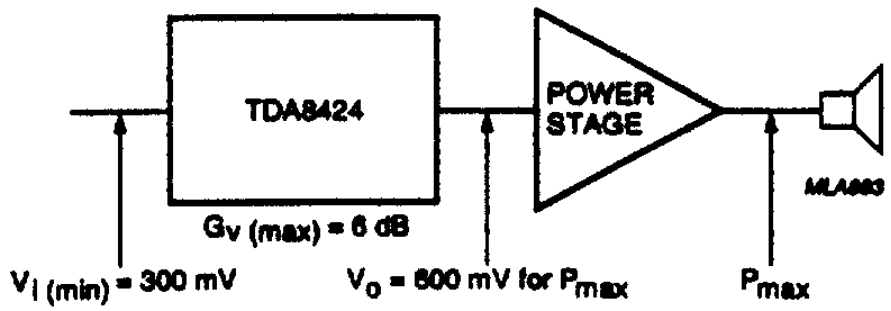


Fig.22 Level diagram.

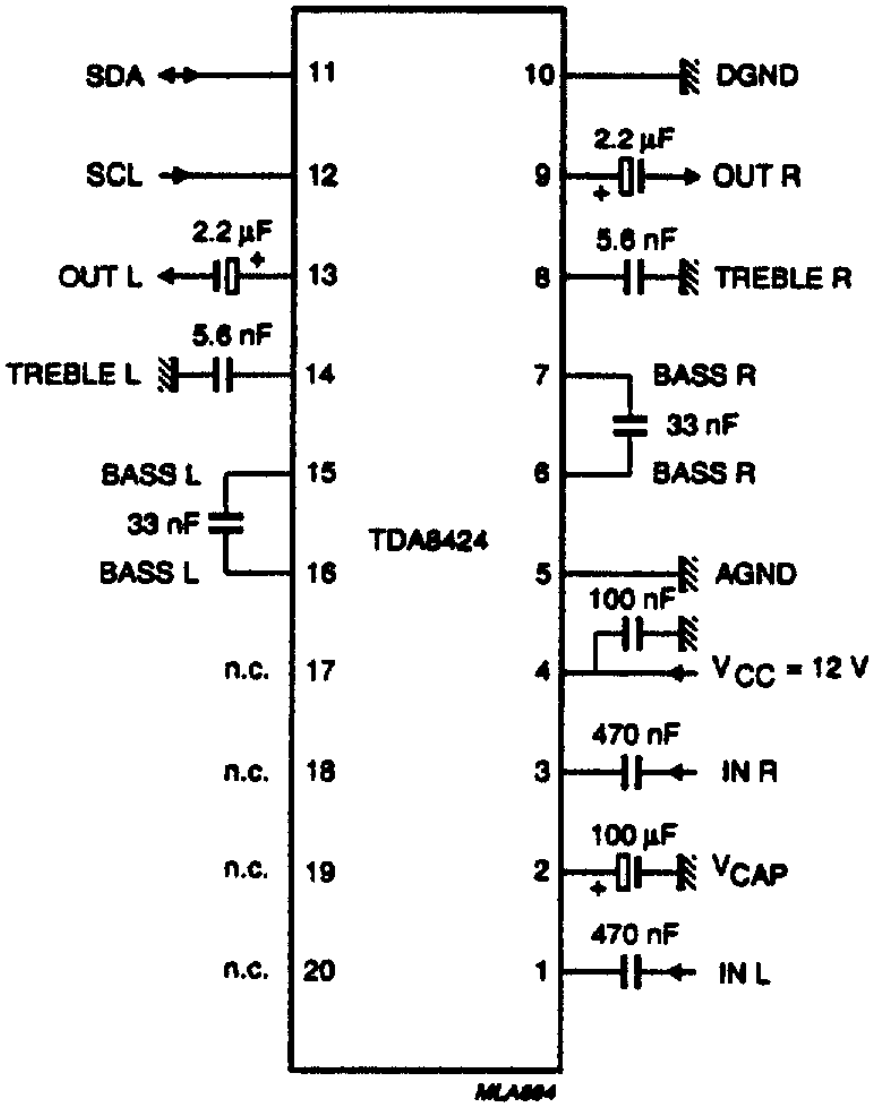
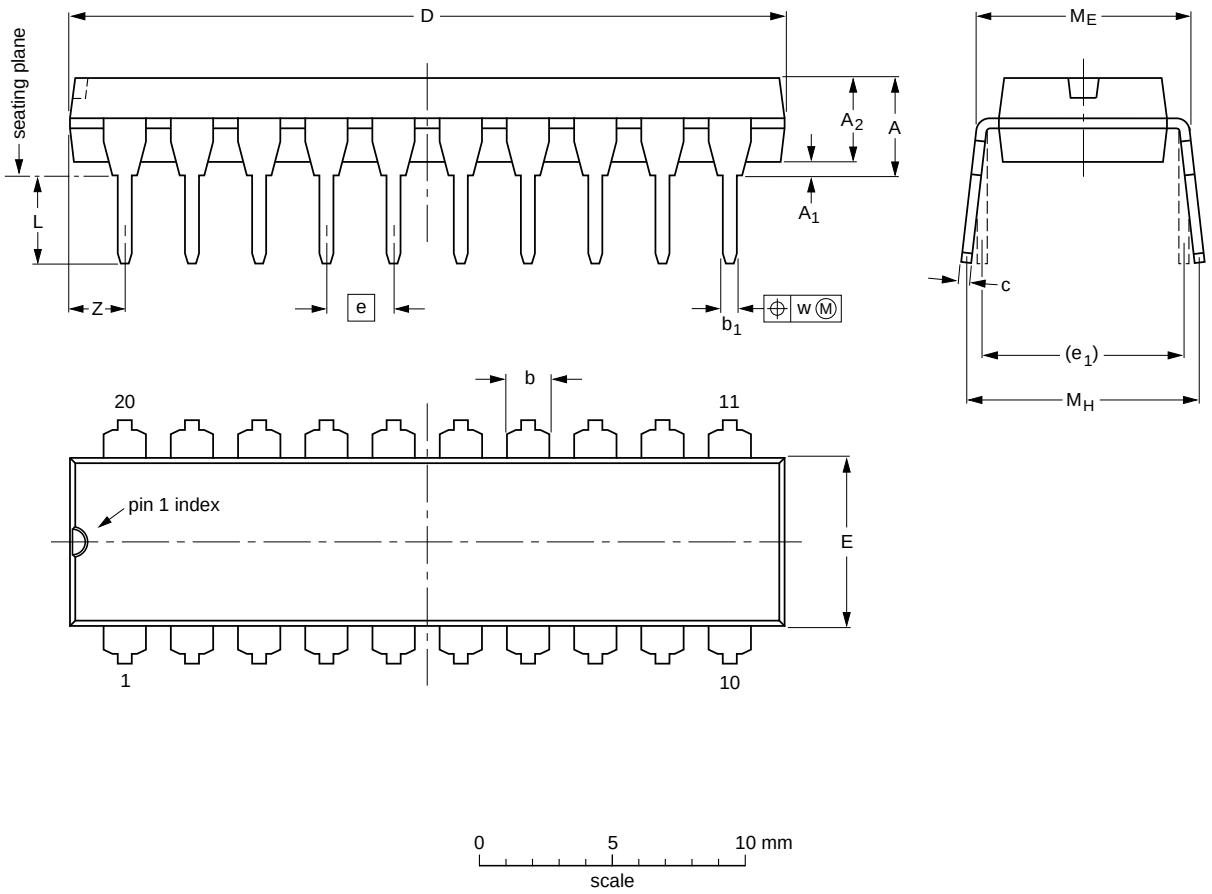


Fig.23 Test and application circuit diagram.

PACKAGE OUTLINE

DIP20: plastic dual in-line package; 20 leads (300 mil) **SOT146-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			~~92-11-17~~ 95-05-24

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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